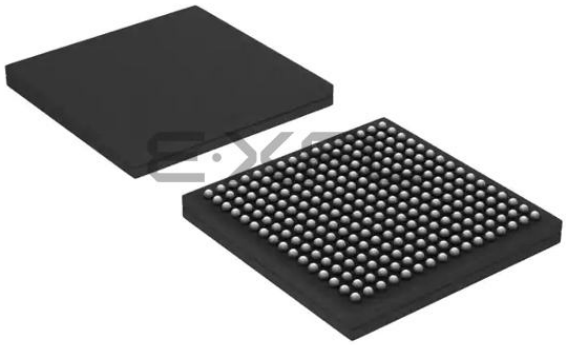

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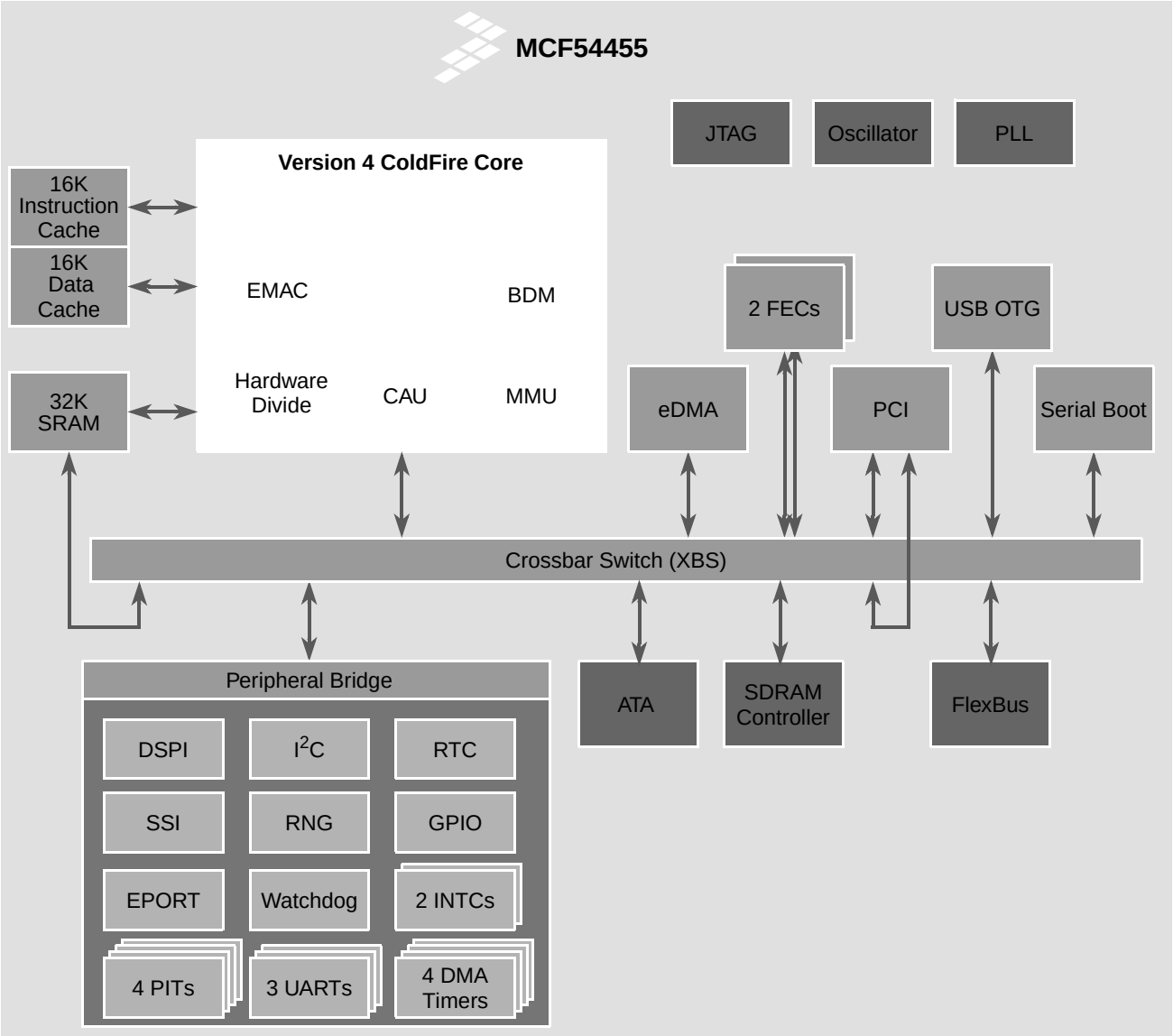
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Coldfire V4
Core Size	32-Bit Single-Core
Speed	240MHz
Connectivity	I²C, SPI, SSI, UART/USART, USB OTG
Peripherals	DMA, WDT
Number of I/O	132
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.35V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-MAPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mcf54450vm240j



LEGEND

ATA	– Advanced Technology Attachment Controller	**INTC**	– Interrupt controller
BDM	– Background debug module	**JTAG**	– Joint Test Action Group interface
CAU	– Cryptography acceleration unit	**MMU**	– Memory management unit
DSPI	– DMA serial peripheral interface	**PCI**	– Peripheral Component Interconnect
eDMA	– Enhanced direct memory access	**PIT**	– Programmable interrupt timers
EMAC	– Enchance multiply-accumulate unit	**PLL**	– Phase locked loop module
EPORT	– Edge port module	**RNG**	– Random Number Generator
FEC	– Fast Ethernet controller	**RTC**	– Real time clock
GPIO	– General Purpose Input/Output	**SSI**	– Synchronous Serial Interface
I^{2}C	– Inter-Intergrated Circuit	**USB OTG**	– Universal Serial Bus On-the-Go controller

Figure 1. MCF54455 Block Diagram

2 Ordering Information

Table 2. Orderable Part Numbers

Freescale Part Number	Description	Package	Speed	Temperature
MCF54450CVM180	MCF54450 Microprocessor	256 MAPBGA	180 MHz	–40° to +85° C
MCF54450VM240			240 MHz	0° to +70° C
MCF54451CVM180	MCF54451 Microprocessor		180 MHz	–40° to +85° C
MCF54451VM240			240 MHz	0° to +70° C
MCF54452CVR200	MCF54452 Microprocessor	360 TEPBGA	200 MHz	–40° to +85° C
MCF54452YVR200			200 MHz	–40° to +105° C
MCF54452VR266			266 MHz	0° to +70° C
MCF54453CVR200	MCF54453 Microprocessor		200 MHz	–40° to +85° C
MCF54453VR266			266 MHz	0° to +70° C
MCF54454CVR200	MCF54454 Microprocessor		200 MHz	–40° to +85° C
MCF54454VR266			266 MHz	0° to +70° C
MCF54455CVR200	MCF54455 Microprocessor		200 MHz	–40° to +85° C
MCF54455VR266			266 MHz	0° to +70° C

3 Hardware Design Considerations

3.1 Analog Power Filtering

To further enhance noise isolation, an external filter is strongly recommended for the analog V_{DD} pins (VDD_A_PLL, VDD_RTC). The filter shown in Figure 2 should be connected between the board IV_{DD} and the analog pins. The resistor and capacitors should be placed as close to the dedicated analog V_{DD} pin as possible. The 10-Ω resistor in the given filter is required. Do not implement the filter circuit using only capacitors. The analog power pins draw very little current. Concerns regarding voltage loss across the 10-ohm resistor are not valid.

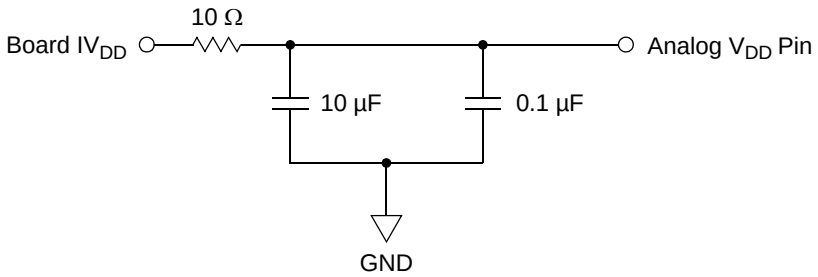


Figure 2. System Analog V_{DD} Power Filter

3.2 Oscillator Power Filtering

Figure 3 shows an example for isolating the oscillator power supply from the I/O supply (EVDD) and ground.

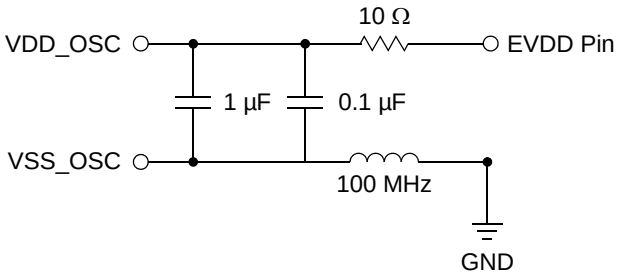
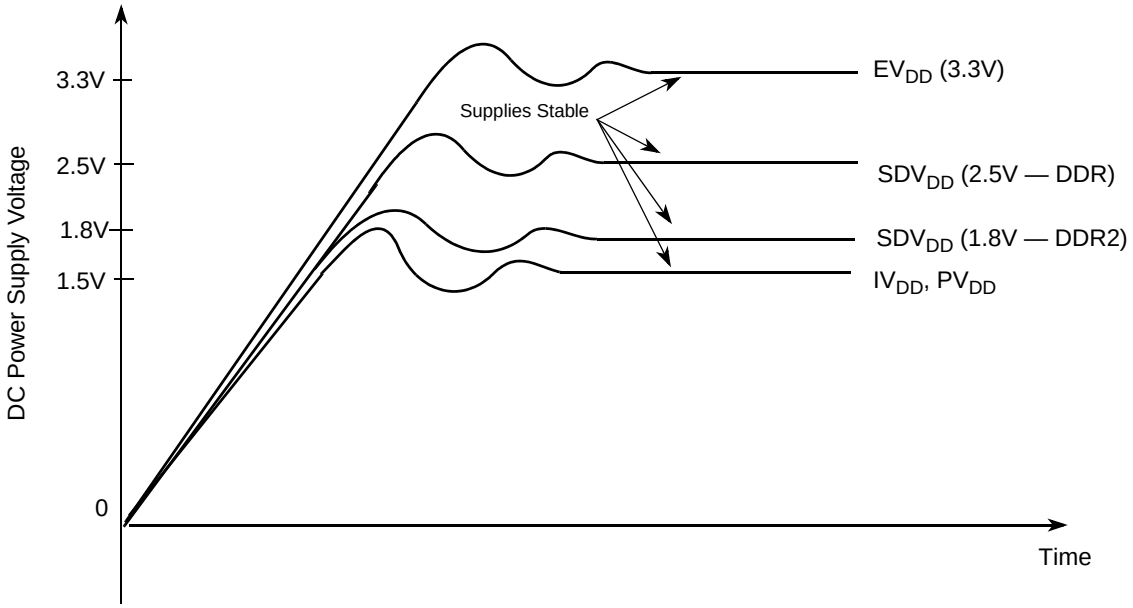


Figure 3. Oscillator Power Filter

3.3 Supply Voltage Sequencing

Figure 4 shows situations in sequencing the I/O V_{DD} (EV_{DD}), SDRAM V_{DD} (SDV_{DD}), PLL V_{DD} (PV_{DD}), and internal logic/core V_{DD} (IV_{DD}).



Notes:
1. Input voltage must not be greater than the supply voltage (EV_{DD}, SDV_{DD}, IV_{DD}, or PV_{DD}) by more than 0.5V at any time, including during power-up.
2. Use 50 V/millisecond or slower rise time for all supplies.

Figure 4. Supply Voltage Sequencing and Separation Cautions

The relationship between SDV_{DD} and EV_{DD} is non-critical during power-up and power-down sequences. SDV_{DD} (2.5V or 1.8V) and EV_{DD} are specified relative to IV_{DD}.

3.3.1 Power-Up Sequence

If EV_{DD}/SDV_{DD} are powered up with the IV_{DD} at 0 V, the sense circuits in the I/O pads cause all pad output drivers connected to the EV_{DD}/SDV_{DD} to be in a high impedance state. There is no limit on how long after EV_{DD}/SDV_{DD} powers up before IV_{DD} must power up. The rise times on the power supplies should be slower than 50 V/millisecond to avoid turning on the internal ESD protection clamp diodes.

3.3.2 Power-Down Sequence

If IV_{DD}/PV_{DD} are powered down first, sense circuits in the I/O pads cause all output drivers to be in a high impedance state. There is no limit on how long after IV_{DD} and PV_{DD} power down before EV_{DD} or SDV_{DD} must power down. There are no requirements for the fall times of the power supplies.

4 Pin Assignments and Reset States

4.1 Signal Multiplexing

The following table lists all the MCF5445*x* pins grouped by function. The Dir column is the direction for the primary function of the pin only. Refer to Section 4, “Pin Assignments and Reset States,” for package diagrams. For a more detailed discussion of the MCF5445*x* signals, consult the *MCF54455 Reference Manual* (MCF54455RM).

NOTE

In this table and throughout this document, a single signal within a group is designated without square brackets (i.e., FB_AD23), while designations for multiple signals within a group use brackets (i.e., FB_AD[23:21]) and is meant to include all signals within the two bracketed numbers when these numbers are separated by a colon.

NOTE

The primary functionality of a pin is not necessarily its default functionality. Most pins that are muxed with GPIO default to their GPIO functionality. See Table 3 for a list of the exceptions.

Table 3. Special-Case Default Signal Functionality

Pin	256 MAPBGA	360 TEPBGA
FB_AD[31:0]	FB_AD[31:0] except when serial boot selects 0-bit boot port size.	
$\overline{\text{FB\_BE/BWE}}$[3:0]	$\overline{\text{FB\_BE/BWE}}$[3:0]	
$\overline{\text{FB\_CS}}$[3:1]	$\overline{\text{FB\_CS}}$[3:1]	
$\overline{\text{FB\_OE}}$	$\overline{\text{FB\_OE}}$	
FB_R/$\overline{\text{W}}$	FB_R/$\overline{\text{W}}$	
$\overline{\text{FB\_TA}}$	$\overline{\text{FB\_TA}}$	
$\overline{\text{FB\_TS}}$	$\overline{\text{FB\_TS}}$	

Table 4. MCF5445*x* Signal Information and Muxing (continued)

Signal Name	GPIO	Alternate 1	Alternate 2	Pull-up (U)[1] Pull-down (D)	Direction[2]	Voltage Domain	MCF54450 MCF54451 256 MAPBGA	MCF54452 MCF54453 MCF54454 MCF54455 360 TEPBGA
FB_TS	PFBCTL0	FB_ALE	FB_TBST	—	O	EVDD	A3	Y3
PCI Controller[5]								
PCI_AD[31:0]	—	FB_A[31:0]	—	—	I/O	EVDD	—	C11, D11, A10, B10, J4, G2, G3, F1, D12, C12, B12, A11, B11, B9, D9, D10, A8, B8, A5, B5, A4, A3, B3, D4, D3, E3–E1, F3, C2, D2, C1
—	—	FB_A[23:0]	—	—	I/O	EVDD	K14–13, J15–13, H13–15, G15–13, F14–13, E15–13, D16, B16, C15, B15, C14, D15, C16, D14	—
PCI_CBE[3:0]	—	—	—	—	I/O	EVDD	—	G4, E4, D1, B1
PCI_DEVSEL	—	—	—	—	O	EVDD	—	F2
PCI_FRAME	—	—	—	—	I/O	EVDD	—	B2
PCI_GNT3	PPCI7	ATA_DMACK	—	—	O	EVDD	—	B7
PCI_GNT[2:1]	PPCI[6:5]	—	—	—	O	EVDD	—	C8, C9
PCI_GNT0/ PCI_EXTREQ	PPCI4	—	—	—	O	EVDD	—	A9
PCI_IDSEL	—	—	—	—	I	EVDD	—	D5
PCI_IRDY	—	—	—	—	I/O	EVDD	—	C3
PCI_PAR	—	—	—	—	I/O	EVDD	—	C4
PCI_PERR	—	—	—	—	I/O	EVDD	—	B4
PCI_REQ3	PPCI3	ATA_INTRQ	—	—	I	EVDD	—	C7
PCI_REQ[2:1]	PPCI[2:1]	—	—	—	I	EVDD	—	D7, C5
PCI_REQ0/ PCI_EXTGNT	PPCI0	—	—	—	I	EVDD	—	A2
PCI_RST	—	—	—	—	O	EVDD	—	B6
PCI_SERR	—	—	—	—	I/O	EVDD	—	A6
PCI_STOP	—	—	—	—	I/O	EVDD	—	A7
PCI_TRDY	—	—	—	—	I/O	EVDD	—	C10
SDRAM Controller								
SD_A[13:0]	—	—	—	—	O	SDVDD	R1, P1, N2, P2, R2, T2, M4, N3, P3, R3, T3, T4, R4, N4	V22, U20–22, T19–22, R20–22, N19, P20–21

Table 4. MCF5445*x* Signal Information and Muxing (continued)

Signal Name	GPIO	Alternate 1	Alternate 2	Pull-up (U)[1] Pull-down (D)	Direction[2]	Voltage Domain	MCF54450 MCF54451 256 MAPBGA	MCF54452 MCF54453 MCF54454 MCF54455 360 TEPBGA
FEC0_TXCLK	PFEC0H7	FEC0_RMII_ REF_CLK	—	—	I	EVDD	H4	Y10
FEC0_TXD[3:2]	PFEC0L[7:6]	—	ULPI_DATA[3:2]	—	O	EVDD	J1, J2	W10, AB11
FEC0_TXD1	PFEC0L5	FEC0_RMII_TXD1	—	—	O	EVDD	J3	AA11
FEC0_TXD0	PFEC0H5	FEC0_RMII_TXD0	—	—	O	EVDD	J4	Y11
FEC0_TXEN	PFEC0H6	FEC0_RMII_TXEN	—	—	O	EVDD	K1	W11
FEC0_TXER	PFEC0L4	—	ULPI_DATA0	—	O	EVDD	K2	AB12
FEC1								
FEC1_MDC	PFECI2C5	—	$\overline{\text{ATA\_DIOR}}$	—	O	EVDD	—	W20
FEC1_MDIO	PFECI2C4	—	$\overline{\text{ATA\_DIOW}}$	—	I/O	EVDD	—	Y22
FEC1_COL	PFEC1H4	—	ATA_DATA7	—	I	EVDD	—	AB18
FEC1_CRS	PFEC1H0	—	ATA_DATA6	—	I	EVDD	—	AA18
FEC1_RXCLK	PFEC1H3	—	ATA_DATA5	—	I	EVDD	—	W14
FEC1_RXDV	PFEC1H2	FEC1_RMII_ CRS_DV	ATA_DATA15	—	I	EVDD	—	AB15
FEC1_RXD[3:2]	PFEC1L[3:2]	—	ATA_DATA[4:3]	—	I	EVDD	—	AA15, Y15
FEC1_RXD1	PFEC1L1	FEC1_RMII_RXD1	ATA_DATA14	—	I	EVDD	—	AA17
FEC1_RXD0	PFEC1H1	FEC1_RMII_RXD0	ATA_DATA13	—	I	EVDD	—	Y17
FEC1_RXER	PFEC1L0	FEC1_RMII_RXER	ATA_DATA12	—	I	EVDD	—	W17
FEC1_TXCLK	PFEC1H7	FEC1_RMII_ REF_CLK	ATA_DATA11	—	I	EVDD	—	AB19
FEC1_TXD[3:2]	PFEC1L[7:6]	—	ATA_DATA[2:1]	—	O	EVDD	—	Y19, W18
FEC1_TXD1	PFEC1L5	FEC1_RMII_TXD1	ATA_DATA10	—	O	EVDD	—	AA19
FEC1_TXD0	PFEC1H5	FEC1_RMII_TXD0	ATA_DATA9	—	O	EVDD	—	Y20
FEC1_TXEN	PFEC1H6	FEC1_RMII_TXEN	ATA_DATA8	—	O	EVDD	—	AA21
FEC1_TXER	PFEC1L4	—	ATA_DATA0	—	O	EVDD	—	AA22
USB On-the-Go								
USB_DM	—	—	—	—	O	USB VDD	F16	A14
USB_DP	—	—	—	—	O	USB VDD	E16	A15
USB_VBUS_EN	PUSB1	USB_PULLUP	ULPI_NXT	—	O	USB VDD	E5	AA2
USB_VBUS_OC	PUSB0	—	ULPI_STP	UD[7]	I	USB VDD	B3	V4

Table 4. MCF5445*x* Signal Information and Muxing (continued)

Signal Name	GPIO	Alternate 1	Alternate 2	Pull-up (U)[1] Pull-down (D)	Direction[2]	Voltage Domain	MCF54450 MCF54451 256 MAPBGA	MCF54452 MCF54453 MCF54454 MCF54455 360 TEPBGA
Power Supplies								
IVDD	—	—	—	—	—	—	E6–12, F5, F12	D6, D8, D14, F4, H4, N4, R4, W4, W7, W8, W12, W16, W19
EVDD	—	—	—	—	—	—	G5, G12, H5, H12, J5, J12, K5, K12, L5–6, L12	D13, D19, G8, G11, G14, G16, J7, J16, L7, L16, N16, P7, R16, T8, T12, T14, T16
SD_VDD	—	—	—	—	—	—	L7–11, M9, M10	F19, H19, K19, M19, R19, U19
VDD_OSC	—	—	—	—	—	—	L14	B16
VDD_A_PLL	—	—	—	—	—	—	K15	C14
VDD_RTC	—	—	—	—	—	—	M12	C13
VSS	—	—	—	—	—	—	A1, A16, F6–11, G6–11, H6–11, J6–11, K6–11, T1, T16	A1, A22, B14, G7, G9–10, G12–13, G15, H7, H16, J9–14, K7, K9–14, K16, L9–14, M7, M9–M14, M16, N7, N9–14, P9–14, P16, R7, T7, T9–11, T13, T15, AB1, AB22
VSS_OSC	—	—	—	—	—	—	L15	C16

1 Pull-ups are generally only enabled on pins with their primary function, except as noted.

2 Refers to pin's primary function.

3 Enabled only in oscillator bypass mode (internal crystal oscillator is disabled).

4 Serial boot must select 0-bit boot port size to enable the GPIO mode on these pins.

5 When the PCI is enabled, all PCI bus pins come up configured as such. This includes the PCI_GNT and PCI_REQ lines, which have GPIO. The IRQ1/$\overline{\text{PCI\_INTA}}$ signal is a special case. It comes up as $\overline{\text{PCI\_INTA}}$ when booting as a PCI agent and as GPIO when booting as a PCI host.
For the 360 TEPBGA, booting with PCI disabled results in all dedicated PCI pins being safe-stated. The $\overline{\text{PCI\_GNT}}$ and $\overline{\text{PCI\_REQ}}$ lines and IRQ1/$\overline{\text{PCI\_INTA}}$ come up as GPIO.

6 GPIO functionality is determined by the edge port module. The pin multiplexing and control module is only responsible for assigning the alternate functions.

7 Depends on programmed polarity of the USB_VBUS_OC signal.

8 Pull-up when the serial boot facility (SBF) controls the pin

9 If JTAG_EN is asserted, these pins default to Alternate 1 (JTAG) functionality. The pin multiplexing and control module is not responsible for assigning these pins.

5 Electrical Characteristics

This document contains electrical specification tables and reference timing diagrams for the MCF54455 microprocessor. This section contains detailed information on DC/AC electrical characteristics and AC timing specifications.

The electrical specifications are preliminary and from previous designs or design simulations. These specifications may not be fully tested or guaranteed at this early stage of the product life cycle. However, for production silicon, these specifications will be met. Finalized specifications will be published after complete characterization and device qualifications have been completed.

NOTE

The parameters specified in this MCU document supersede any values found in the module specifications.

5.1 Absolute Maximum Ratings

Table 5. Absolute Maximum Ratings[1, 2]

Rating	Symbol	Pin Name	Value	Units
External I/O pad supply voltage	EV_{DD}	EVDD	-0.3 to +4.0	V
Internal oscillator supply voltage	$OSCV_{DD}$	VDD_OSC	-0.3 to +4.0	V
Real-time clock supply voltage	$RTCV_{DD}$	VDD_RTC	-0.5 to +2.0	V
Internal logic supply voltage	IV_{DD}	IVDD	-0.5 to +2.0	V
SDRAM I/O pad supply voltage	SDV_{DD}	SD_VDD	-0.3 to +4.0	V
PLL supply voltage	PV_{DD}	VDD_A_PLL	-0.5 to +2.0	V
Digital input voltage[3]	V_{IN}	—	-0.3 to +3.6	V
Instantaneous maximum current Single pin limit (applies to all pins) [3, 4, 5]	I_{DD}	—	25	mA
Operating temperature range (packaged)	T_A (T_L - T_H)	—	-40 to +85	°C
Storage temperature range	T_{stg}	—	-55 to +150	°C

1 Functional operating conditions are given in Table 8. Absolute maximum ratings are stress ratings only, and functional operation at the maximum is not guaranteed. Continued operation at these levels may affect device reliability or cause permanent damage to the device.

2 This device contains circuitry protecting against damage due to high static voltage or electrical fields. However, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (e.g., V_{SS} or EV_{DD}).

3 Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values for positive and negative clamp voltages, and then use the larger of the two values.

4 All functional non-supply pins are internally clamped to V_{SS} and EV_{DD}.

5 Power supply must maintain regulation within operating EV_{DD} range during instantaneous and operating maximum current conditions. If positive injection current (V_{in} > EV_{DD}) is greater than I_{DD}, the injection current may flow out of EV_{DD} and could result in external power supply going out of regulation. Ensure the external EV_{DD} load shunts current greater than maximum injection current. This is the greatest risk when the MPU is not consuming power (ex; no clock). The power supply must maintain regulation within operating EV_{DD} range during instantaneous and operating maximum current conditions.

where K is a constant pertaining to the particular part. K can be determined from Equation 3 by measuring P_D (at equilibrium) for a known T_A. Using this value of K, the values of P_D and T_J can be obtained by solving Equation 1 and Equation 2 iteratively for any value of T_A.

5.3 ESD Protection

Table 7. ESD Protection Characteristics[1, 2]

Characteristics	Symbol	Value	Units
ESD Target for Human Body Model	HBM	2000	V

1 All ESD testing is in conformity with CDF-AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits.

2 A device is defined as a failure if after exposure to ESD pulses the device no longer meets the device specification requirements. Complete DC parametric and functional testing is performed per applicable device specification at room temperature followed by hot temperature, unless specified otherwise in the device specification.

5.4 DC Electrical Specifications

Table 8. DC Electrical Specifications

Characteristic	Symbol	Min	Max	Units
Internal logic supply voltage[1]	IV_{DD}	1.35	1.65	V
PLL analog operation voltage range [1]	PV_{DD}	1.35	1.65	V
External I/O pad supply voltage	EV_{DD}	3.0	3.6	V
Internal oscillator supply voltage	$OSCV_{DD}$	3.0	3.6	V
Real-time clock supply voltage	$RTCV_{DD}$	1.35	1.65	V
SDRAM I/O pad supply voltage — DDR mode	SDV_{DD}	2.25	2.75	V
SDRAM I/O pad supply voltage — DDR2 mode	SDV_{DD}	1.7	1.9	V
SDRAM I/O pad supply voltage — Mobile DDR mode	SDV_{DD}	1.7	1.9	V
SDRAM input reference voltage	SDV_{REF}	0.49 x SDV_{DD}	0.51 x SDV_{DD}	V
Input High Voltage	V_{IH}	0.7 x EV_{DD}	3.65	V
Input Low Voltage	V_{IL}	V_{SS} – 0.3	0.35 x EV_{DD}	V
Input Hysteresis	V_{HYS}	0.06 x EV_{DD}	—	mV
Input Leakage Current[2] V_{in} = V_{DD} or V_{SS}, Input-only pins	I_{in}	–2.5	2.5	µA
Input Leakage Current[3] V_{in} = V_{DD} or V_{SS}, Input-only pins	I_{in}	–5	5	µA
High Impedance (Off-State) Leakage Current[4] V_{in} = V_{DD} or V_{SS}, All input/output and output pins	I_{OZ}	–10.0	10.0	µA
Output High Voltage (All input/output and all output pins) I_{OH} = –5.0 mA	V_{OH}	0.85 × EV_{DD}	—	V
Output Low Voltage (All input/output and all output pins) I_{OL} = 5.0mA	V_{OL}	—	0.15 × EV_{DD}	V

Table 9. Input Clock Timing Requirements

Item	Specification	Min	Max	Unit
C1	Cycle time	15	40	ns
1 / C1	Frequency	25	66.66	MHz
C2	Rise time (20% of vdd to 80% of vdd)	-	2	ns
C3	Fall time (80% of vdd to 20% of vdd)	-	2	ns
C4	Duty cycle (at 50% of vdd)	40	60	%

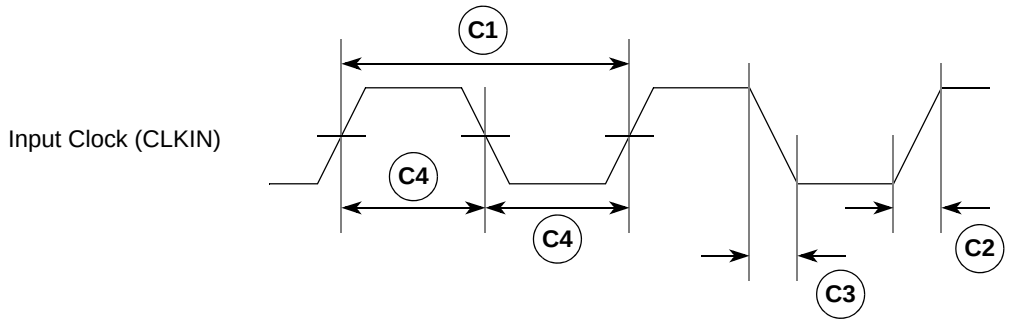


Figure 7. Input Clock Timing Diagram

Table 10. PLL Electrical Characteristics

Num	Characteristic	Symbol	Min. Value	Max. Value	Unit
1	PLL Reference Frequency Range Crystal reference External reference	 $f_{ref\_crystal}$ f_{ref_ext}	 16 16	 40 66.66	 MHz MHz
2	Core/System Frequency	f_{sys}	512 Hz[1]	266.67 MHz	—
	Core/System Clock Period	t_{sys}	—	$1/f_{sys}$	ns
19	VCO Frequency ($f_{vco} = f_{ref} \times PFDR$)	f_{vco}	300	540	MHz
3	Crystal Start-up Time[2, 3]	t_{cst}	—	10	ms
4	EXTAL Input High Voltage Crystal Mode[4] All other modes (External, Limp)	 V_{IHEXT} V_{IHEXT}	 V_{XTAL} + 0.4 $E_{VDD}/2$ + 0.4	 — —	 V V
5	EXTAL Input Low Voltage Crystal Mode[4] All other modes (External, Limp)	 V_{ILEXT} V_{ILEXT}	 — —	 V_{XTAL} - 0.4 $E_{VDD}/2$ - 0.4	 V V
6	EXTAL Input Rise & Fall Time (20% to 80% E_{VDD}) (External, Limp)		1	2	ns
7	PLL Lock Time [3, 5]	t_{lpll}	—	50000	CLKIN
8	Duty Cycle of reference [3] (External, Limp)	t_{dc}	40	60	%
9	XTAL Current	I_{XTAL}	1	3	mA
10	Total on-chip stray capacitance on XTAL	C_{S_XTAL}	—	1.5	pF

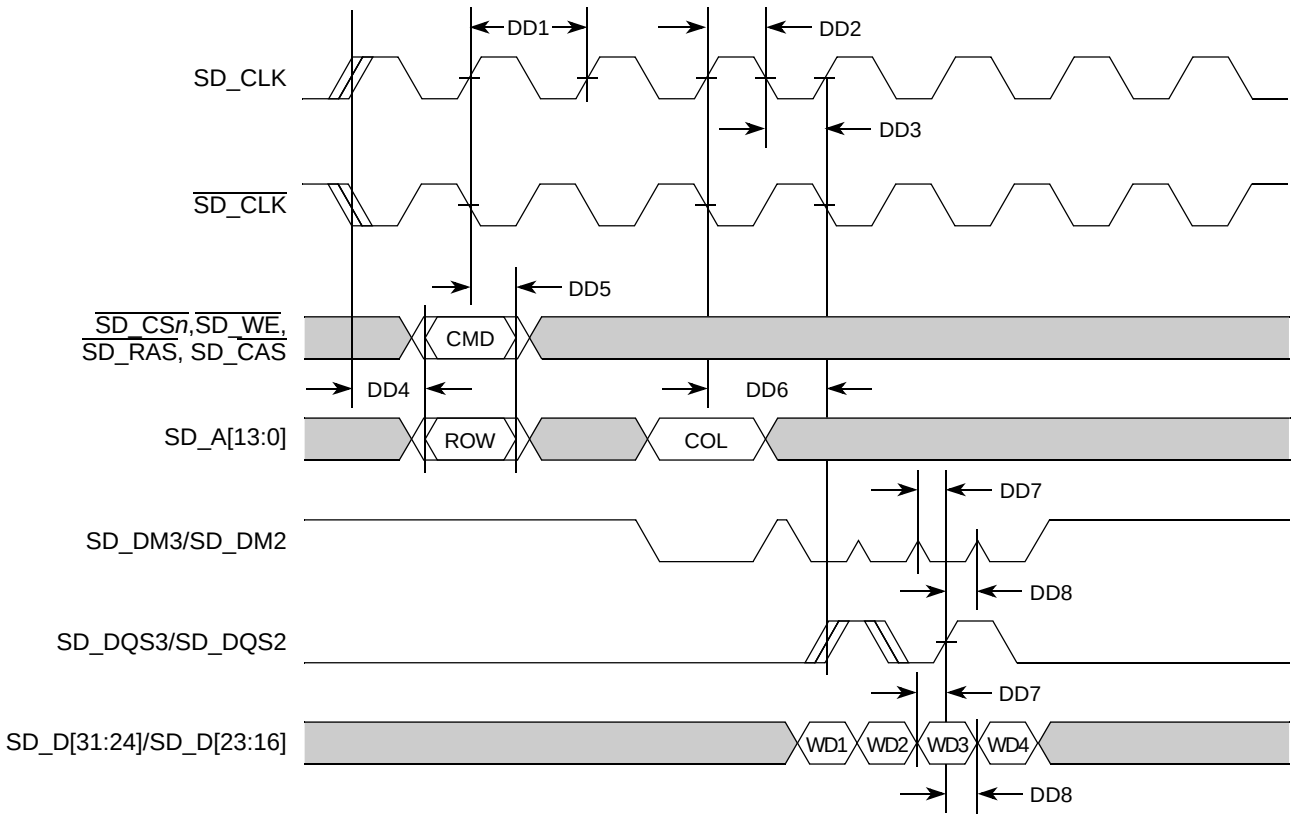


Figure 11. DDR Write Timing

Table 14. PCI Timing Specifications[1,2] (continued)

Num	Characteristic	33 MHz[3]		66 MHz[3]		
		Min	Max	Min	Max	Unit
P6	$\overline{\text{PCI\_REQ}}$[3:0]/$\overline{\text{PCI\_GNT}}$[3:0] — output valid	—	12.0	—	6.0	ns
P7	All PCI signals — output hold	2.0	—	1.0	—	ns

1 The PCI bus operates at the CLKIN frequency. All timings are relative to the input clock, CLKIN.

2 All PCI signals are bused signals except for PCI_GNT[3:0] and PCI_REQ[3:0]. These signals are defined as point-to-point signals by the PCI Specification.

3 The 66-MHz parameters are only guaranteed when the 66-MHz PCI pad slew rates are selected. Likewise, the 33-MHz parameters are only guaranteed when the 33-MHz PCI pad slew rates are selected.

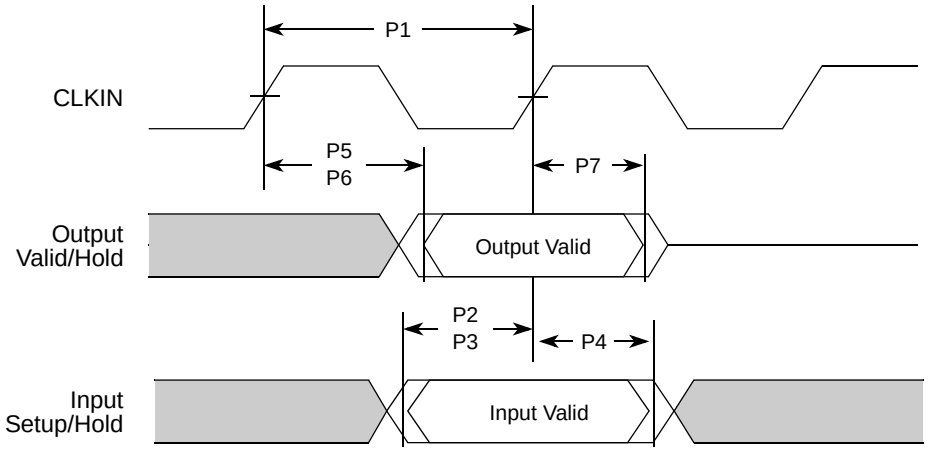


Figure 13. PCI Timing

5.9.1 Overshoot and Undershoot

Figure 14 shows the specification limits for overshoot and undershoot for PCI I/O. To guarantee long term reliability, the specification limits shown must be followed. Good transmission line design practices should be observed to guarantee the specification limits.

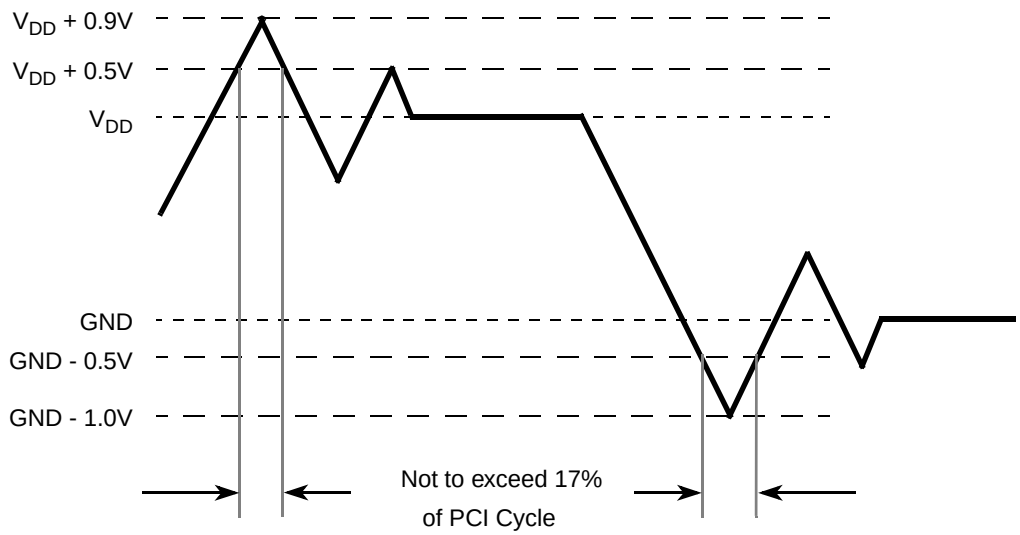


Figure 14. Overshoot and Undershoot Limits

5.10 ULPI Timing Specifications

The ULPI interface is fully compliant with the industry standard UTMI+ Low Pin Interface. Control and data timing requirements for the ULPI pins are given in Table 15. These timings apply to synchronous mode only. All timings are measured with respect to the clock as seen at the USB_CLKIN pin on the MCF5445*x*. The ULPI PHY is the source of the 60MHz clock.

NOTE

The USB controller requires a 60-MHz clock, even if using the on-chip FS/LS transceiver instead of the ULPI interface. In this case, the 60-MHz clock can be generated by the PLL or input on the USB_CLKIN pin.

Table 15. ULPI Interface Timing

Num	Characteristic	Min	Nominal	Max	Units
	USB_CLKIN operating frequency	—	60	—	MHz
	USB_CLKIN duty cycle	—	50	—	%
U1	USB_CLKIN clock period	—	16.67	—	ns
U2	Input Setup (control and data)	5.0	—	—	ns
U3	Input Hold (control and data)	1.0	—	—	ns
U4	Output Valid (control and data)	—	—	9.5	ns
U5	Output Hold (control and data)	1.0	—	—	

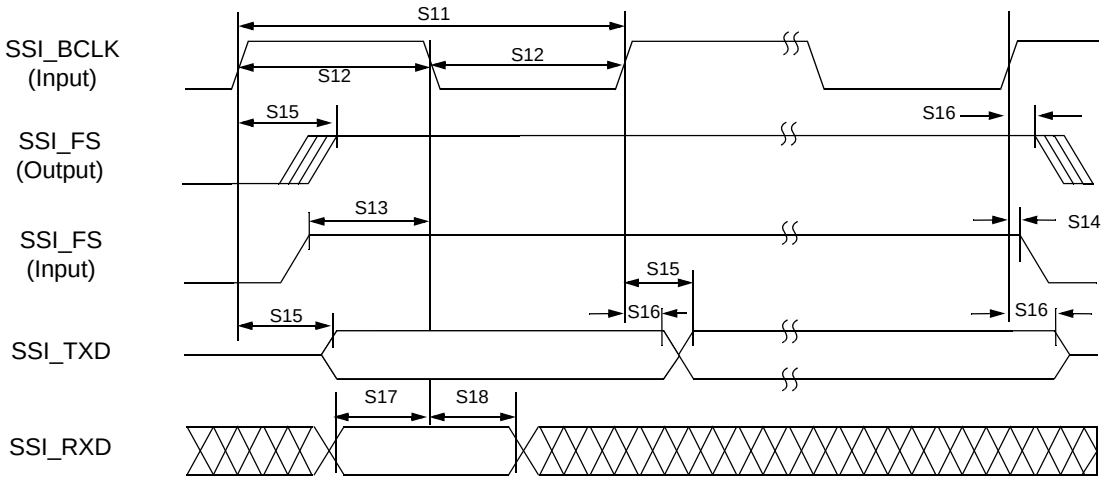


Figure 17. SSI Timing—Slave Modes

5.12 I²C Timing Specifications

Table 18 lists specifications for the I²C input timing parameters shown in Figure 18.

Table 18. I²C Input Timing Specifications between SCL and SDA

Num	Characteristic	Min	Max	Units
I1	Start condition hold time	2	—	t_{SYS}
I2	Clock low period	8	—	t_{SYS}
I3	I2C_SCL/I2C_SDA rise time (V_{IL} = 0.5 V to V_{IH} = 2.4 V)	—	1	ms
I4	Data hold time	0	—	ns
I5	I2C_SCL/I2C_SDA fall time (V_{IH} = 2.4 V to V_{IL} = 0.5 V)	—	1	ms
I6	Clock high time	4	—	t_{SYS}
I7	Data setup time	0	—	ns
I8	Start condition setup time (for repeated start condition only)	2	—	t_{SYS}
I9	Stop condition setup time	2	—	t_{SYS}

Table 19 lists specifications for the I²C output timing parameters shown in Figure 18.

Table 19. I²C Output Timing Specifications between SCL and SDA

Num	Characteristic	Min	Max	Units
I1[1]	Start condition hold time	6	—	t_{SYS}
I2[1]	Clock low period	10	—	t_{SYS}
I3[2]	I2C_SCL/I2C_SDA rise time (V_{IL} = 0.5 V to V_{IH} = 2.4 V)	—	—	µs
I4[1]	Data hold time	7	—	t_{SYS}
I5[3]	I2C_SCL/I2C_SDA fall time (V_{IH} = 2.4 V to V_{IL} = 0.5 V)	—	3	ns

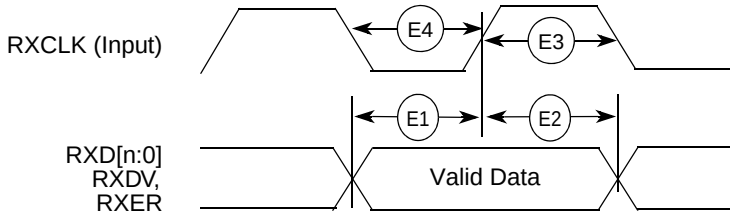


Figure 19. MII Receive Signal Timing Diagram

5.13.2 Transmit Signal Timing Specifications

Table 21. Transmit Signal Timing

Num	Characteristic	MII Mode		RMII Mode		Unit
		Min	Max	Min	Max	
—	TXCLK frequency	—	25	—	50	MHz
E5	TXCLK to TXD[n:0], TXEN, TXER invalid[1]	5	—	5	—	ns
E6	TXCLK to TXD[n:0], TXEN, TXER valid[1]	—	25	—	14	ns
E7	TXCLK pulse width high	35%	65%	35%	65%	t_{TXCLK}
E8	TXCLK pulse width low	35%	65%	35%	65%	t_{TXCLK}

1 In MII mode, n = 3; In RMII mode, n = 1

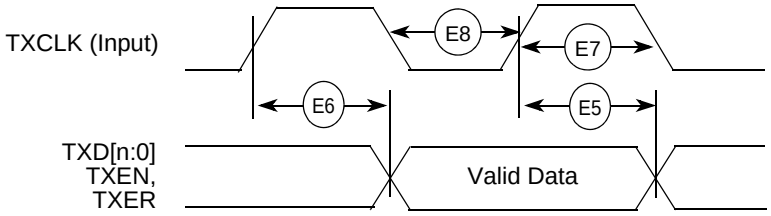


Figure 20. MII Transmit Signal Timing Diagram

5.13.3 Asynchronous Input Signal Timing Specifications

Table 22. MII Transmit Signal Timing

Num	Characteristic	Min	Max	Unit
E9	CRS, COL minimum pulse width	1.5	—	TXCLK period

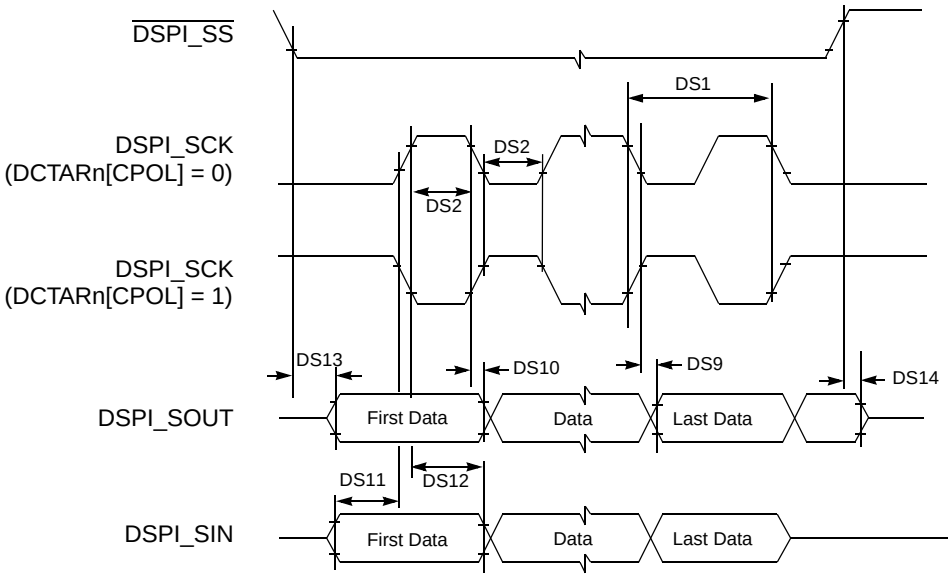


Figure 24. DSPI Classic SPI Timing—Slave Mode

5.17 SBF Timing Specifications

The Serial Boot Facility (SBF) provides a means to read configuration information and system boot code from a broad array of SPI-compatible EEPROMs, flashes, FRAMs, nVSRAMs, etc. Table 27 provides the AC timing specifications for the SBF.

Table 27. SBF AC Timing Specifications

Name	Characteristic	Symbol	Min	Max	Unit	Notes
SB1	SBF_CK Cycle Time	t_{SBFCK}	40	—	ns	[1]
SB2	SBF_CK High/Low Time	—	30%	—	t_{SBFCK}	
SB3	$\overline{\text{SBF\_CS}}$ to SBF_CK delay	—	t_{SBFCK} - 2.0	—	ns	
SB4	SBF_CK to $\overline{\text{SBF\_CS}}$ delay	—	t_{SBFCK} - 2.0	—	ns	
SB5	SBF_CK to SBF_DO valid	—	-5	—	ns	
SB6	SBF_CK to SBF_DO invalid	—	5	—	ns	
SB7	SBF_DI to SBF_SCK input setup	—	10	—	ns	
SB8	SBF_CK to SBF_DI input hold	—	0	—	ns	

[1] At reset, the SBF_CK cycle time is $t_{REF} \times 67$. The first byte of data read from the serial memory contains a divider value that is used to set the SBF_CK cycle time for the duration of the serial boot process.

5.19 JTAG and Boundary Scan Timing

Table 29. JTAG and Boundary Scan Timing

Num	Characteristics[1]	Min	Max	Unit
J1	TCLK Frequency of Operation	DC	20	MHz
J2	TCLK Cycle Period	50	—	ns
J3	TCLK Clock Pulse Width	20	30	ns
J4	TCLK Rise and Fall Times	—	3	ns
J5	Boundary Scan Input Data Setup Time to TCLK Rise	5	—	ns
J6	Boundary Scan Input Data Hold Time after TCLK Rise	20	—	ns
J7	TCLK Low to Boundary Scan Output Data Valid	—	33	ns
J8	TCLK Low to Boundary Scan Output High Z	—	33	ns
J9	TMS, TDI Input Data Setup Time to TCLK Rise	4	—	ns
J10	TMS, TDI Input Data Hold Time after TCLK Rise	10	—	ns
J11	TCLK Low to TDO Data Valid	—	11	ns
J12	TCLK Low to TDO High Z	—	11	ns
J13	$\overline{\text{TRST}}$ Assert Time	50	—	ns
J14	$\overline{\text{TRST}}$ Setup Time (Negation) to TCLK High	10	—	ns

1 JTAG_EN is expected to be a static signal. Hence, specific timing is not associated with it.

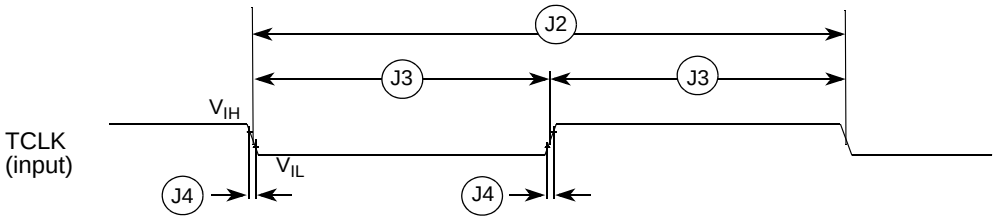


Figure 27. Test Clock Input Timing

All current consumption data is lab data measured on a single device using an evaluation board. Table 32 shows the typical power consumption in low-power modes. These current measurements are taken after executing a STOP instruction.

Table 32. Current Consumption in Low-Power Modes[1,2]

Mode	Voltage Supply	System Frequency				
		166 (Typ)[3]	200 (Typ)[3]	233 (Typ)[3]	266 (Typ)[3]	266 (Peak)[4]
RUN	IV_{DD} (mA)	93.4	110.9	128.2	145.4	202.1
	Power (mW)	140.1	166.3	192.4	218.1	303.2
WAIT/DOZE	IV_{DD} (mA)	28.0	32.7	37.5	41.1	100.2
	Power (mW)	42.0	49.1	56.2	61.7	150.3
STOP 0	IV_{DD} (mA)	17.1	19.8	22.5	25.2	25.2
	Power (mW)	25.7	29.7	33.7	37.8	37.8
STOP 1	IV_{DD} (mA)	17.9	19.8	22.4	25.1	25.1
	Power (mW)	26.8	29.6	33.6	37.6	37.6
STOP 2	IV_{DD} (mA)	5.7	5.7	5.7	5.7	5.7
	Power (mW)	8.6	8.6	8.6	8.6	8.6
STOP 3	IV_{DD} (mA)	1.8	1.8	1.8	1.8	1.8
	Power (mW)	2.6	2.6	2.6	2.6	2.6

1 All values are measured on an M54455EVB with 1.5V IV_{DD} power supply. Tests performed at room temperature.

2 Refer to the Power Management chapter in the *MCF54455 Reference Manual* for more information on low-power modes.

3 All peripheral clocks are off except UART0, INTC0, IACK, edge port, reset controller, CCM, PLL, and FlexBus prior to entering low-power mode.

4 All peripheral clocks on prior to entering low-power mode.

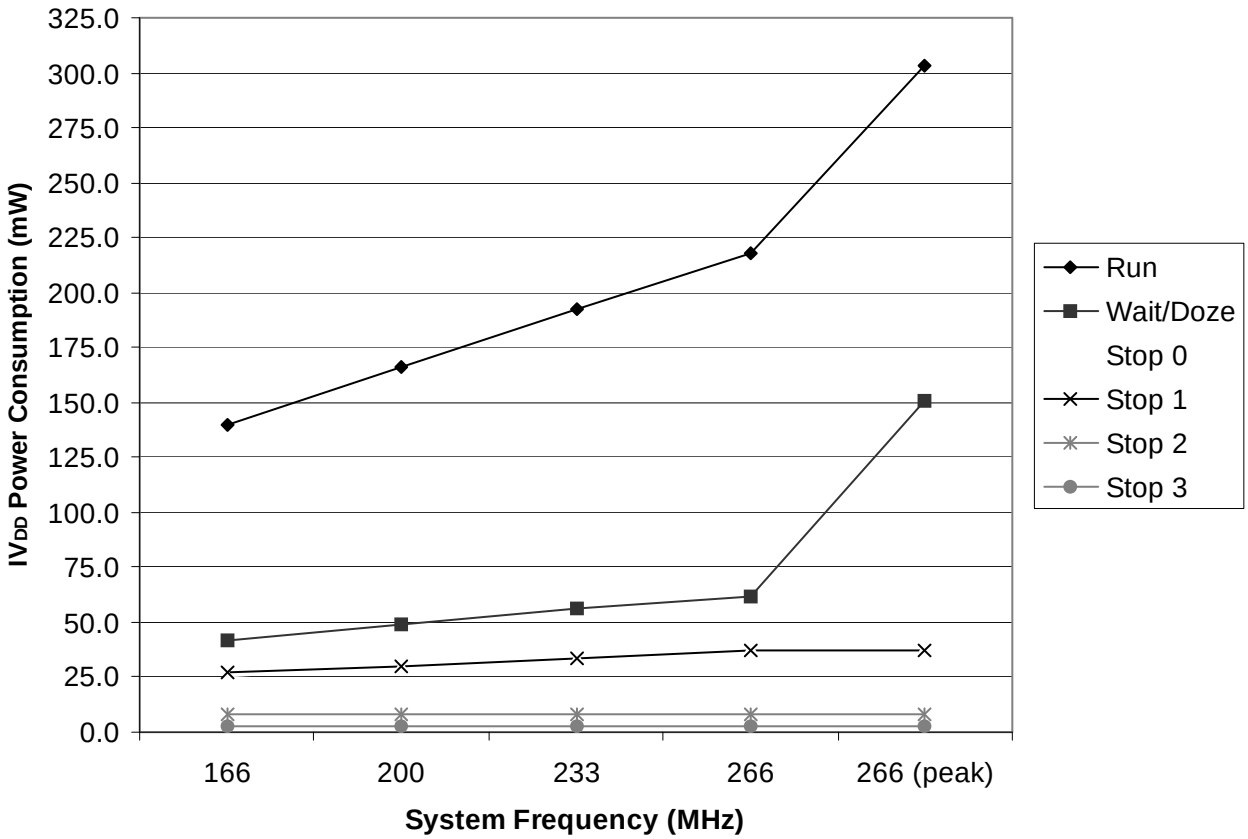


Figure 34. IV_{DD} Power Consumption in Low-Power Modes

7 Package Information

The latest package outline drawings are available on the product summary pages on http://www.freescale.com/coldfire. Table 33 lists the case outline numbers per device. Use these numbers in the web page's keyword search engine to find the latest package outline drawings.

Table 33. Package Information

Device	Package Type	Case Outline Numbers
MCF54450	256 MAPBGA	98ARH98219A
MCF54451		
MCF54452	360 TEPBGA	98ARE10605D
MCF54453		
MCF54454		
MCF54455		

8 Product Documentation

Documentation is available from a local Freescale distributor, a Freescale sales office, the Freescale Literature Distribution Center, or through the Freescale world-wide web address at http://www.freescale.com/coldfire.

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Document Number: MCF54455
Rev. 8
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